

Amendments to the Specification:

Please replace paragraph [0020] as follows:

[00020] As shown in Figure 2a, the electrical component and/or chip 20 may be disposed upon a card or board 26. In another embodiment, as illustrated in Figure 2b, more than one electrical component and/or chip 20a-c may be situated upon a single card 26. In the case of several chips 20a-c, the implementation of the invention may be achieved with a single means for regulating the operating voltage 22ab of more than one chip 20a and 20b. Alternatively, the voltage of each chip may be regulated individually by a chip-specific means for regulating the operating voltage 22c, or, a chip-specific means for regulating the voltage 22c may be used together with another means for regulating the voltage 22a,b of more than one chip. For example, depending upon the semiconductor material or the operating function of the chip, the nominal operating voltage as well as the minimum allowed operating voltage (per the instant invention) of each chip may be different. In this instance, chip-specific means 22c for regulating voltage may be preferred. In cases where the multiple chips have similar operating voltages, a single means for regulating voltage 22ab may be employed. If a remote thermometer is used, a single means for measuring the temperature 24 of all of the chips 20a-c may be employed. Alternatively, each chip 20a-c may have its own thermometer (integrated thermal diode for example).